

SN74LVC10A Triple 3-Input Positive-NAND Gate

1 Features

- Operates from 1.65V to 3.6V
- Specified from -40°C to 85°C and -40°C to 125°C
- Inputs accept voltages to 5.5V
- Max t_{pd} of 4.9ns at 3.3V
- Typical V_{OLP} (output ground bounce) $< 0.8\text{V}$ at $V_{CC} = 3.3\text{V}$, $T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (output V_{OH} undershoot) $> 2\text{V}$ at $V_{CC} = 3.3\text{V}$, $T_A = 25^{\circ}\text{C}$
- Latch-up performance exceeds 250 mA per JESD 17
- ESD protection exceeds JESD 22
 - 2000V human-body model (A114-A)

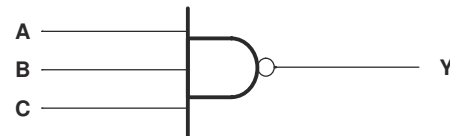
2 Description

This triple 3-input positive-NAND gate is designed for 1.65V to 3.6V V_{CC} operation.

Package Information

PART NUMBER	PACKAGE SIZE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE ⁽³⁾
SN74LVC10A	BQA (WQFN, 14)	3mm × 2.5mm	3mm × 2.5mm
	D (SOIC, 14)	8.65mm × 6mm	8.65mm × 3.9mm
	DB (SSOP, 14)	6.2mm × 7.8mm	6.2mm × 5.3mm
	NS (SOP, 14)	10.2mm × 7.8mm	10.3mm × 5.3mm
	PW (TSSOP, 14)	5mm × 6.4mm	5mm × 4.4mm
	RGY (VQFN, 14)	3.5mm × 3.5mm	3.5mm × 3.5mm

- For more information, see [Section 10](#).
- The package size (length × width) is a nominal value and includes pins, where applicable.
- The body size (length × width) is a nominal value and does not include pins.



Logic Diagram, Each Gate (Positive Logic)



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3 Pin Configuration and Functions

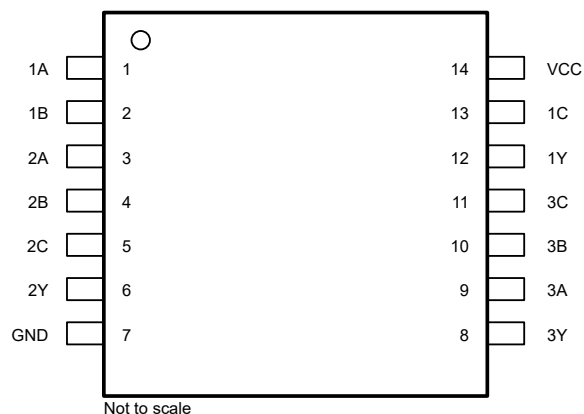


Figure 3-1. SN74LVC10A D, DB, NS, or PW Packages; 14-Pin SOIC, SSOP, SOP, or TSSOP (Top View)

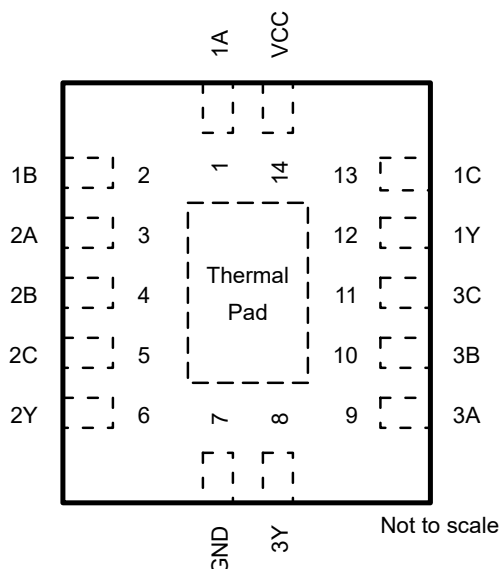


Figure 3-2. SN74LVC10A BQA Package, 14-Pin WQFN (Top View)

Table 3-1. Pin Functions

PIN		I/O ⁽¹⁾	DESCRIPTION
NAME	NO.		
1A	1	Input	Channel 1, Input A
1B	2	Input	Channel 1, Input B
2A	3	Input	Channel 2, Input A
2B	4	Input	Channel 2, Input B
2C	5	Input	Channel 2, Input C
2Y	6	Output	Channel 2, Output Y
GND	7	—	Ground
3Y	8	Output	Channel 3, Output Y
3A	9	Input	Channel 3, Input A
3B	10	Input	Channel 3, Input B
3C	11	Input	Channel 3, Input C
1Y	12	Output	Channel 1, Output Y
1C	13	Input	Channel 1, Input C
V _{CC}	14	—	Positive Supply
Thermal pad		—	Connect the GND pin to the exposed thermal pad for correct operation. Connect the thermal pad to any internal PCB ground plane using multiple vias for good thermal performance.

(1) I = input, O = output, P = power, FB = feedback, GND = ground, N/A = not applicable

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	–0.5	6.5	V
V_I	Input voltage range ⁽¹⁾	–0.5	6.5	V
V_O	Output voltage range ^{(1) (2)}	–0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		–50 mA
I_{OK}	Output clamp current	$V_O < 0$		–50 mA
I_O	Continuous output current		±50	mA
	Continuous current through V_{CC} or GND		±100	mA
T_{stg}	Storage temperature range	–65	150	°C
P_{tot}	Power dissipation	$T_A = -40^{\circ}\text{C}$ to 125°C ^{(3) (4)}		500 mW

(1) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(2) The value of V_{CC} is provided in the recommended operating conditions table.

(3) For the D package: above 70°C , the value of P_{tot} derates linearly with 8 mW/K.

(4) For the DB, NS, and PW packages: above 60°C , the value of P_{tot} derates linearly with 5.5 mW/K.

4.2 ESD Ratings

	VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000 V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

4.3 Recommended Operating Conditions

			T _A = 25°C		–40 TO 85°C		–40 TO 125°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65V to 1.95V	0.65 × V _{CC}		0.65 × V _{CC}		0.65 × V _{CC}		V
		V _{CC} = 2.3V to 2.7V	1.7		1.7		1.7		
		V _{CC} = 2.7V to 3.6V	2		2		2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65V to 1.95V	0.35 × V _{CC}		0.35 × V _{CC}		0.35 × V _{CC}		V
		V _{CC} = 2.3V to 2.7V	0.7		0.7		0.7		
		V _{CC} = 2.7V to 3.6V	0.8		0.8		0.8		
V _I	Input voltage		0	5.5	0	5.5	0	5.5	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65V	–4		–4		–4		mA
		V _{CC} = 2.3V	–8		–8		–8		
		V _{CC} = 2.7V	–12		–12		–12		
		V _{CC} = 3V	–24		–24		–24		
I _{OL}	Low-level output current	V _{CC} = 1.65V	4		4		4		mA
		V _{CC} = 2.3V	8		8		8		
		V _{CC} = 2.7V	12		12		12		
		V _{CC} = 3V	24		24		24		

4.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74LVC10A						UNIT
		BQA (WQFN)	D (SOIC)	DB (SSOP)	NS (SOP)	PW (TSSOP)	RGY (VQFN)	
		14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	102.3	86	96	76	113	47	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

4.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

For recommended operating free air temperature range (unless otherwise noted)										
PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			–40 TO 85°C		–40 TO 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –100μA	1.65V to 3.6V	V _{CC} – 0.2			V _{CC} – 0.2		V _{CC} – 0.3		V
	I _{OH} = –4mA	1.65V	1.29			1.2		1.05		
	I _{OH} = –8mA	2.3 V	1.9			1.7		1.55		
	I _{OH} = –12mA	2.7V	2.2			2.2		2.05		
		3V	2.4			2.4		2.25		
	I _{OH} = –24mA	3V	2.3			2.2		2		
V _{OL}	I _{OL} = 100μA	1.65V to 3.6V	0.1			0.2		0.3		V
	I _{OL} = 4mA	1.65V	0.24			0.45		0.6		
	I _{OL} = 8mA	2.3V	0.3			0.7		0.75		
	I _{OL} = 12mA	2.7V	0.4			0.4		0.6		
	I _{OL} = 24mA	3V	0.55			0.55		0.8		
I _I	V _I = 5.5V or GND	3.6V	±1			±5		±20		μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6V	1			10		40		μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7V to 3.6V	500			500		5000		μA
C _i	V _I = V _{CC} or GND	3.3V	5							pF

4.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			–40 TO 85°C		–40 TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A, B, or C	Y	1.8V ± 0.15V	1	4.2	10.1	1	10.6	1	12.1	ns
			2.5V ± 0.2V	1	2.9	7.3	1	7.8	1	9.9	
			2.7V	1	3.1	5.6	1	5.8	1	7.4	
			3.3V ± 0.3V	1	2.7	4.7	1	4.9	1	6	
t _{sk(o)}			3.3V ± 0.3V				1		1.5		ns

4.7 Operating Characteristics

$T_A = 25^\circ\text{C}$

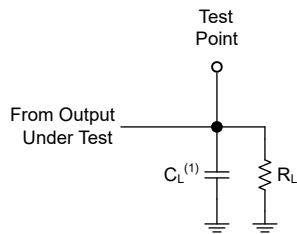
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance per gate	$f = 10\text{ MHz}$	1.8V	9	pF
			2.5V	10	
			3.3V	11	

5 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily for the examples listed in the following table. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{MHz}$, $Z_O = 50\Omega$, $t_f \leq 2.5\text{ns}$.

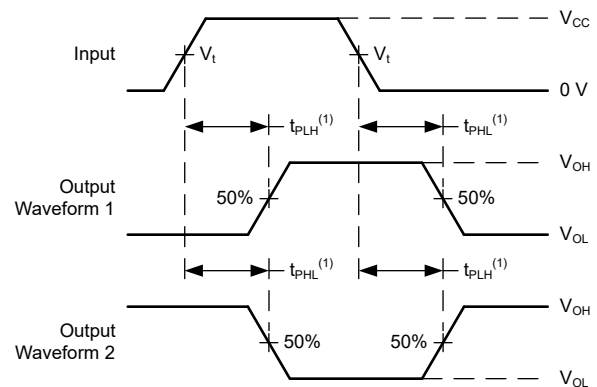
The outputs are measured individually with one input transition per measurement.

V_{CC}	V_t	R_L	C_L	ΔV
$1.8\text{V} \pm 0.15\text{V}$	$V_{CC}/2$	$1\text{k}\Omega$	30pF	0.15V
$2.5\text{V} \pm 0.2\text{V}$	$V_{CC}/2$	500Ω	30pF	0.15V
2.7V	1.5V	500Ω	50pF	0.3V
$3.3\text{V} \pm 0.3\text{V}$	1.5V	500Ω	50pF	0.3V



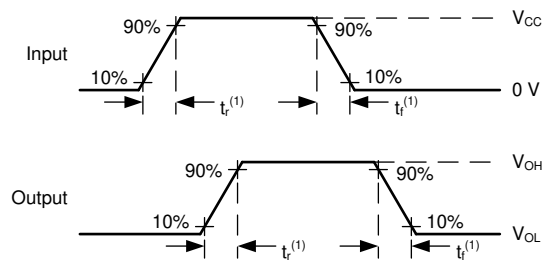
(1) C_L includes probe and test-fixture capacitance.

Figure 5-1. Load Circuit for Push-Pull Outputs



(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd} .

Figure 5-2. Voltage Waveforms Propagation Delays



(1) The greater between t_r and t_f is the same as t_t .

Figure 5-3. Voltage Waveforms, Input and Output Transition Times

6 Detailed Description

6.1 Overview

The SN74LVC10A performs the Boolean function $Y = \overline{A \cdot B \cdot C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

Inputs can be driven from either 3.3V or 5V devices. This feature allows the use of these devices as translators in a mixed 3.3V/5V system environment.

6.2 Functional Block Diagram

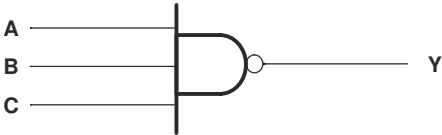


Figure 6-1. Logic Diagram, Each Gate (Positive Logic)

6.3 Device Functional Modes

Table 6-1. Function Table
(Each Gate)

INPUTS			OUTPUT Y
A	B	C	
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating in the [Recommended Operating Conditions](#).

Each V_{CC} pin must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 μF is recommended; if there are multiple V_{CC} pins, then 0.01 μF or 0.022 μF is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 μF and a 1 μF are commonly used in parallel. The bypass capacitor must be installed as close to the power pin as possible for best results.

7.2 Layout

7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

7.2.2 Layout Example

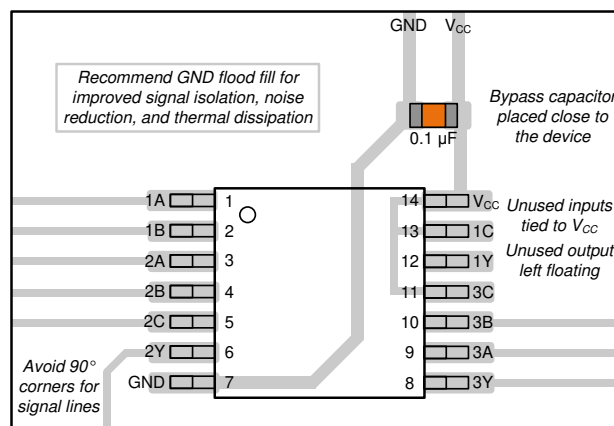


Figure 7-1. Example layout for the SN74LVC10A

8 Device and Documentation Support

8.1 Documentation Support (Analog)

8.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to order now.

Table 8-1. Related Links

PARTS	PRODUCT FOLDER	ORDER NOW	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LVC10A	Click here	Click here	Click here	Click here	Click here

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision O (July 2005) to Revision P (May 2024)	Page
• Added BQA package to <i>Package Information</i> table, <i>Pin Configuration and Functions</i> section, and <i>Thermal Information</i> table.....	1
• Added <i>Applications</i> section, <i>Package Information</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	1
• Deleted machine model from <i>Features</i> section.....	1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC10AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC10A	Samples
SN74LVC10ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC10A	Samples
SN74LVC10ADG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC10A	Samples
SN74LVC10ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC10A	Samples
SN74LVC10ADT	ACTIVE	SOIC	D	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC10A	Samples
SN74LVC10ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC10A	Samples
SN74LVC10APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC10A	Samples
SN74LVC10APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC10A	Samples
SN74LVC10APWT	ACTIVE	TSSOP	PW	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC10A	Samples
SN74LVC10ARGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC10A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC10ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LVC10ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC10ADT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC10ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVC10APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC10APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC10ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC10ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LVC10ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LVC10ADT	SOIC	D	14	250	210.0	185.0	35.0
SN74LVC10ANSR	SO	NS	14	2000	356.0	356.0	35.0
SN74LVC10APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LVC10APWT	TSSOP	PW	14	250	356.0	356.0	35.0
SN74LVC10ARGYR	VQFN	RGY	14	3000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LVC10AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVC10ADG4	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVC10APW	PW	TSSOP	14	90	530	10.2	3600	3.5

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-2/I 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



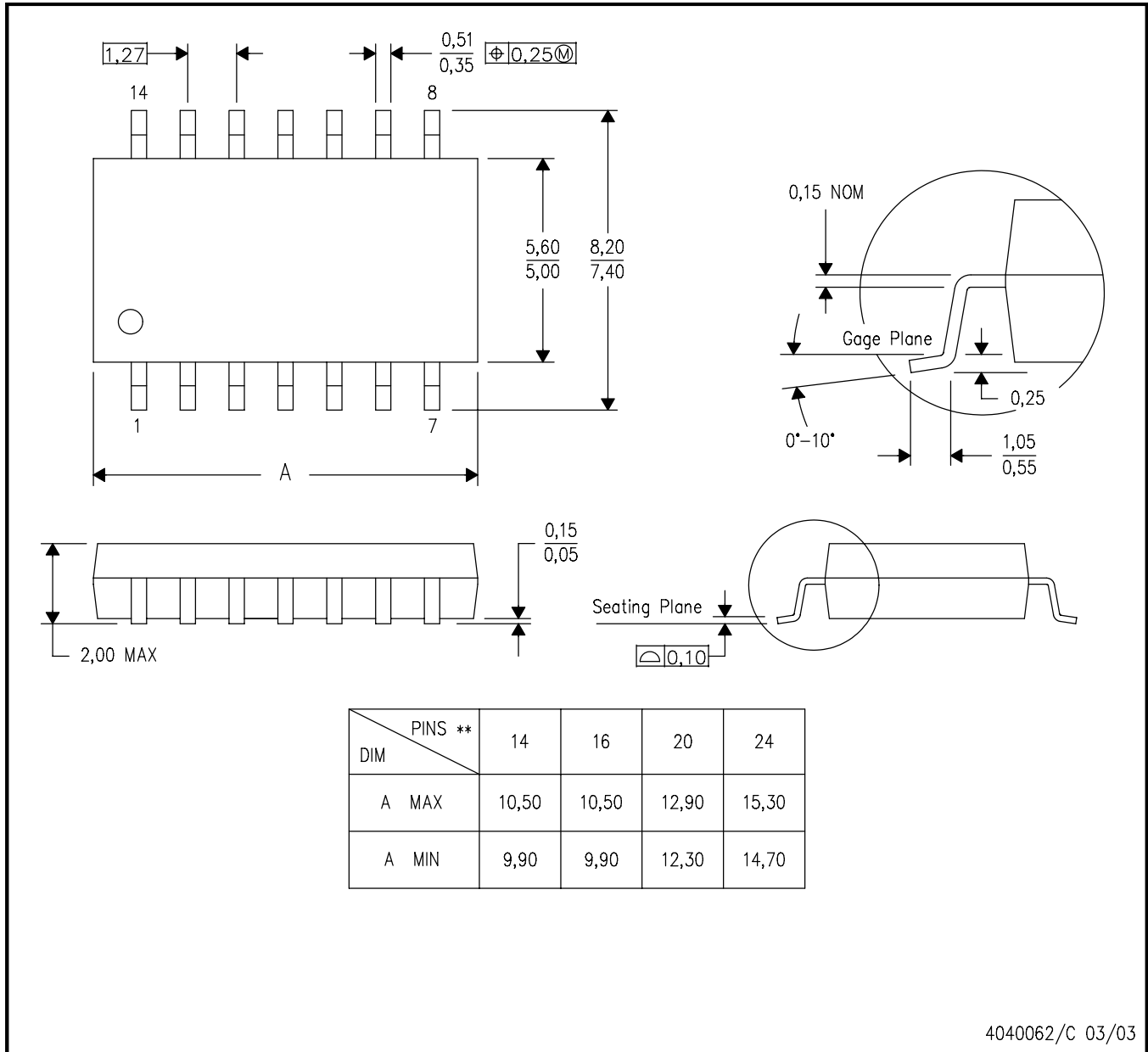
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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